

# Imagination

### **Oberon – M2M IoT Platform**

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## Contents

- Iot Segments and Definitions
- Targeted Use Cases for IoT
- Oberon targeted use cases
- IoT Differentiators
  - IoT Power Management
  - IoT Security
  - Integrated Connectivity
  - Software
- Schedule



## **IoT Market Definition – End Application Segments**



2000 2001 2002 2003 2004 2005 2006 2007 2008 2009 2010 2011 2012 2013 2014 2015 2016 2017 2018 2019 2020

Source: ABI, Nov. 2013

## **IOT Application by Comms data rate requirements**



#### Majority of IOT applications handled by BT, 802.15.4, and 802.11n



## **IoT Use Cases**

	loT (M2M DATA) (Oberon)	loT (Audio) (Hyperion)	loT (video/camera) (Triton)
Device example	Personal health; Sensor Hubs; Smart home Energy management.	Wireless audio	Chromecast Connected camera Video analytics
CPU performance	< 250 DMIPs	300 – 800 DMIPS	2000 - 5000DMIPS
OS requirement	RTOS or No OS	Linux/Android or RTOS	Linux/Android
Power requirements (battery operation)	>1 year (0.1% duty cycle) on 700mA-hr coin cell	Line operated	Line operated
Connectivity	802.15.4/BTLE/802.11n	802.15.4/BTLE + 802.11n/ac	802.11ac + BTLE
Semicon process	55/40nm	40nm/28 nm	28nm / 16ff
Differentiators	<ul> <li>Security –secure boot, OTA update, virtualization</li> <li>Low power</li> <li>Support customer specifications for power management and power policy control</li> <li>Integrated wireless connectivity</li> <li>Cloud ready</li> </ul>		

#### 

## **Oberon - Scope**

Use Cases

Configuration	IoT sensors	IoT M2M	IoT Sensor HUB	IoT Security
Sensor inputs	1	3+	3+	3+
Communications	802.15.4, BTLE	802.15.4, BTLE	BTLE, 15.4,WiFi	BTLE, 15.4, WiFi
Power Management	DVS, DFS, Memory retention support	DVS, DFS, Memory retention support	DVS, DFS, Memory retention support	DVS, DFS, Memory retention support
Security Omnishield™ Ready	<ul><li>Secure boot</li><li>AES/DES</li><li>DPA resistance</li></ul>	<ul> <li>Secure boot</li> <li>AES/DES</li> <li>DPA resistance</li> <li>HW Virtualization</li> </ul>	<ul><li>Secure boot</li><li>AES/DES</li><li>DPA resistance</li><li>HW Virtualization</li></ul>	<ul> <li>Secure boot</li> <li>AES/DES</li> <li>DPA resistance</li> <li>HW Virtualization</li> </ul>
Memory CPU Bange	<ul> <li>Retention SRAM – 64KB</li> <li>FLASH 64K – 1MB SYS +10-20 MIPS</li> </ul>	<ul> <li>Retention SRAM – 64KB</li> <li>FLASH 64K –1MB SYS + 10-100 MIPS</li> </ul>	<ul> <li>Retention SRAM – to 256KB</li> <li>FLASH 512KB – 2MB SYS + 10-100 MIPS</li> </ul>	<ul> <li>Retention SRAM – 64KB</li> <li>FLASH 512K – 2MB SYS + 10-200 MIPS</li> </ul>
Battery Life	1 yr – 3yr	1yr+	515 · 10 100 Will 5	1 yr+

## **Oberon - Scope**

Use Cases

Configuration	IoT sensors	IoT M2M	IoT Sensor HUB	IoT Security
Sensor inputs	1	6+	3+	3+
Communications	802.15.4, BTLE	BTLE, 15.4, WiFi	BTLE, 15.4,WiFi	BTLE, 15.4, WiFi
Power Management	DVS, DFS, Memory retention support	DVS, DFS, Memory retention support	DVS, DFS, Memory retention support	DVS, DFS, Memory retention support
Security	Secure boot	Set reboot	<ul> <li>Secure boot</li> </ul>	St ure boot
Omnishield™ Ready	<ul><li>AES/DES</li><li>DPA resistance</li></ul>	DPA resista	<ul> <li>AES/DES</li> <li>DPA resictation</li> <li>HW Vir ua) zution</li> </ul>	<ul> <li>AES/DES</li> <li>DTA 12 ist nce</li> <li>HW Virtualization</li> </ul>
Memory	<ul> <li>Reten for SrAM – 64KB</li> <li>FLASH 41 – MB</li> </ul>	64KB FLASH 64K –1MB	<ul> <li>Retention SRAN</li> <li>FLASH - 2MB</li> </ul>	Retention SRAM – 64KB FLASH 512K – 2MB
CPU Range	SO+ N2 MIPS	SYS + 10-100 MIPS	SYS + 10-100 MIPS	SYS + 10-200 MIPS
Battery Life	yr – 3yr	1yr+	lyr	1yr — 5yr

## **Oberon - IoT Smart Hub**



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IMG IP

**IMGworks** 

3<sup>rd</sup> Partv

## **IOT – Oberon Smart Hub**

#### Key Features

- Configurable Comms
  - Dual Communication Subsystems includes transceiver and base band
    - 802.15.4 / BTLE
      - Integrated 2.4Ghz transceiver and base band'
      - Power output to +3dBm
    - Low power WiFi (802.11n 1x1)
      - Integrated transceiver, base band, and AFE
      - Integrated PA @+16dBm.
- Omnishield<sup>™</sup> Ready Secure CPU subsystem
  - M-Class 5150 CPU with 32k L1 caches
    - Secure boot
    - Hardware virtualization
    - 150Mhz clock / 540 Coremark
    - DPA Resistance
  - On die 1.5 MB flash memory
  - 320KB System SRAM
  - Up to 128 KB retention memory
  - Encryption DMA
  - Private key Accelerator
  - OTP keys
  - Random number generator

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#### Power management

- Integrated programmable voltage regulators
- Supports DFS/DVS
- Customer defined Power Management Policy
- Operating/Sleep (with data retention) / hibernate modes
- Peripherals
- 2x I2C
- 3x UART
- 3xl2S (2 input, 1 output)
- 3x SPI
- SDIO slave
- 16/32 GPIO
- Analog support
  - 8ch 12 bit A/D @1MHz
- Technology TSMC 40uLP
- Operating voltage:
  - 3.3v (battery or line powered)
- Die Size: 24.5 mm<sup>2</sup>
- Package 36 pin to 100 pin QFN



## Oberon - IoT Smart Device



10

IMG IP

**IMGworks** 

3<sup>rd</sup> Partv

## **IOT – Oberon Smart Device**



#### Key Features

- Configurable Comms
  - BLE/802.15.4 Communication Subsystems includes transceiver and base band
    - Integrated 2.4Ghz transceiver and base band'
    - Power output: to +3dBm
- Omnishield<sup>™</sup> Ready Secure CPU subsystem
  - M-Class 5150 CPU with 32k L1 caches
    - Secure boot
    - Hardware virtualization
    - 150Mhz clock / 540 Coremark
    - DPA Resistance
  - On die 1MB flash memory
  - Up to 64KB retention memory
  - 128KB System SRAM
  - Encryption DMA
  - Private key Accelerator
  - OTP keys
  - Random number generator

- Power management
  - Integrated programmable voltage regulators
  - Supports DFS/DVS
  - Customer defined Power Management Policy
  - Operating/Sleep (with data retention) / hibernate modes
- Peripherals
- 2x I2C
- 3x UART
- 3xI2S (2 input, 1 output)
- 3x SPI
- SDIO slave
- 16/32 GPIO
- Analog support
  - 8ch 12 bit A/D @1MHz
- Technology TSMC 40uLP
- Operating voltage:
  - 3.3v (battery or line powered)
- Die Size: 13.8 mm<sup>2</sup>
- Package 36 pin to 100 pin QFN

## **Oberon Differentiation for IoT**

- Power management
- Security Omnishield<sup>™</sup> ready
- Integrated Wireless Connectivity
- Seamless interface from device to cloud





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### **IoT Power Management**

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## Features of IoT Power Management Control Block

- Provide the hardware support for voltage scaling and frequency scaling
- Provide the hardware support for enabling the power modes for each functional block that will have power down modes.
- Contain an always on 32Khz Time of Day clock.
- Provide counter/timers
- Provide external inputs that will enable the chip (or regions in the chip to assume specific power modes.
- Provide control for power mode policy

**Integrated Switching and Linear Regulators** 



## **Power Management Architecture**



- Support dynamic voltage scaling
- Support dynamic frequency scaling
- Power management wrapper defined for IP.

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## **CPU and RPU Power Optimization**

#### • Uses Power optimized std cell libraries and memories

- Narrow libraries (7 track, 9 track)
- Low power optimized library
- o Power management kit to support voltage islands, power gating, etc.
- $\,\circ\,$  Low power memories with leakage control
- $_{\odot}\,$  Low data retention voltage (0.66v).

#### Defined Power modes

Power State	Power applied	Clocks applied
On	V <sub>DD</sub> Nominal	F <sub>CLK</sub> = Full speed
Idle	V <sub>DD</sub> Reduced	F <sub>CLK</sub> = Reduced
Sleep	$V_{\text{DD}}$ MIN only for memory and F/F state retention	$F_{CLK}$ = gated off
Off	V <sub>DD</sub> Off	F <sub>CLK</sub> = gated off

#### 

## Targeted Power 40 nm – embedded MIPS M5150

#### MIPS embedded CPU

IP block	Power Mode	Supply voltage	Power consumption (est).	Other
M5150 CPU	Active	0.81v	M5150: 32K I\$ and D\$ - 3.2 mW Core: 1.8mW (9uW/Mhz)	200Mhz
M5150 CPU	Active	0.75v	M5150: 32K I\$ and D\$ - 1.6 mW Core: 0.8mW (8uW/Mhz)	100Mhz
M5150 CPU	Data retention mode	0.66v	<500 nW	



## **Targeted Power 40nm – Wireless Comms**

Standard <sup>1</sup>	Transmit	Receive	Connected Standby	Deep Sleep
802.11 b/g/n 1x1 11n Output Power (10 dBm / 16 dBm)	240 mW 684 mW	72 mW	80uW (DTIM-3) 30uW (sleep mode)	1.2 uW
BLE 0 dBm output	9 mW	8 mW	N/A	< 1.0 uW
802.15.4 3 dBm output	< 40 mw	< 12 mW	N/A	< 1.0 uW

<sup>1</sup>All power numbers include transceiver, baseband, and AFE





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### **Oberon Security Features**

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## Security– Omnishield<sup>™</sup> Ready

Provides TPM and common security functions

- Secure Boot
- Secure Code updates
- Key Protection
- DPA resistant
- Access Control of Secure resources
- Enables system level secure mode of operation
- Secure DMA Channel for critical functions
- Run time Integrity Checks



## **Platform Security Subsystem**



- Integrates security for secure boot, secure SW update, CRDMA, OTP keys, PKA
- Provides Root of Trust upon power up.
- Security Subsystem is inside crypto boundary
- Security IP Subsystem is a licensable product





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### **IoT Integrated Wireless Connectivity**

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## **Wireless Connectivity Subsystems**



#### Low Power WIFI subsystem

- $\circ$  Single band 2.4Ghz radio + Integrated PA to +16dBm
- Includes Whisper BB + WiFi AFE + transceiver
- o Compliant to 802.11n
- o Supports soft AP, WiFi Direct, and client modes
- Subsystem IP certified on Oberon

BLE / 802.15.4 2.4 GHz RF / AFE	Whisper WiFi BB BLE / 802.15.4	Fabric IF
Low Power BLE	/ 802.15.4 Sub-S	system

#### BTLE / 802.15.4 subsystem

- Single band 2.4Ghz plus integrated PA to +3dBm
- $\,\circ\,$  Includes Whisper BB + AFE + transceiver
- $\,\circ\,$  Subsystem IP qualification on Oberon
- $\,\circ\,$  optimized for low power 8 mW TX and RX power



## Imagination

#### IoT Seamless Interface from Device to Cloud

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## IoT Software architecture



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## **Oberon Schedule**

#### Specification

- High Level Specification
- Detailed Specification
- Oberon Tapeout
- Silicon bring up platform
- Customer development platform
- Software
  - Contiki
  - FreeRTOS
  - Customer specified

- June 30, 2015
- Aug. 2015
- Q3/2016
- Q4/2016
- Q4/2016
- Q2/2016
- Q3/2016
- TBD

## **Platform Business Model**

### Phase 1: Chip development

- NRE fee covers the following
  - Finalize chip level spec requirements
  - IP license
  - Development of the chip RTL and gdsii
  - Tape out MPW for samples; Customer typically gets up to 100 samples
    - Customer to confirm samples meet requirement.



## **Typical Business Model (2)**

## Phase 2: Production

- Customer has two options
  - Option 1: Customer take to production
    - Chip manufacturing license fee, royalty per unit.
    - Customer proceeds by himself to take to production
  - Option 2: Imagination or its 3<sup>rd</sup> party production partner takes to production
    - Customer pays manufacturing tooling costs including:
      - Package development
      - Masks
      - Reliability qualification